

Product Change Notification - SYST-13AKYW007

Date:

14 Mar 2019

Product Category:

Power Management - Power Switches

Affected CPNs:

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Notification subject:

Data Sheet - MIC94080/1/2/3/4/5 Data Sheet

Notification text:

SYST-13AKYW007

Microchip has released a new DeviceDoc for the MIC94080/1/2/3/4/5 Data Sheet of devices. If you are using one of these devices please read the document located at MIC94080/1/2/3/4/5 Data Sheet.

Notification Status: Final

Description of Change: 1) Converted Micrel document MIC94080/1/2/3/4/5 to Microchip data

sheet template DS20006118A. 2) Minor grammatical text changes throughout

Impacts to Data Sheet: None

Reason for Change: To Improve Manufacturability

Change Implementation Status: Complete

Date Document Changes Effective: 14 Mar 2019

NOTE: Please be advised that this is a change to the document only the product has not been

changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachment(s):

MIC94080/1/2/3/4/5 Data Sheet

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

SYST-13AKYW007 - Data Sheet - MIC94080/1/2/3/4/5 Data Sheet

Affected Catalog Part Numbers (CPN)

MIC94080YFT-TR

MIC94081YFT-TR

MIC94082YFT-TR

MIC94083YFT-TR

MIC94084YFT-TR

MIC94085YFT-TR

Date: Thursday, March 14, 2019



67 m Ω R_{DS(ON)} 2A High-Side Load Switch in 0.85 mm x 0.85 mm FTDFN Package

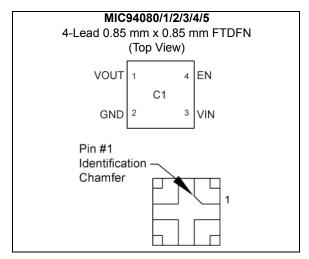
Features

- Space-Saving 0.85 mm x 0.85 mm 4-Lead FTDFN Package
- Input Voltage Range: 1.7V to 5.5V
- · 2A Continuous Operating Current
- 67 mΩ R_{DS(ON)}
- Internal Level Shift for CMOS/TTL Control Logic
- · Ultra-Low Quiescent Current
- · Micropower Shutdown Current
- Soft-Start: MIC94082/3 (800 μs), MIC94084/5 (120 μs)
- Load Discharge Circuit: MIC94081, MIC94083, MIC94085
- Ultra-Fast Turn-Off Time
- –40°C to +125°C Junction Operating Temperature

Applications

- · Cellular Phones
- Portable Navigation Devices (PND)
- · Personal Media Players (PMP)
- · Ultra-Mobile PCs
- · Portable Instrumentation
- Other Portable Applications
- PDAs
- GPS Modules
- · Industrial and Datacom Equipment

Package Type



General Description

The MIC94080/1/2/3/4/5 is a family of high-side load switches designed to operate from 1.7V to 5.5V input voltage. The load switch pass element is an internal 67 m Ω R_{DS(ON)} P-Channel MOSFET that enables the device to support up to 2A of continuous current. Additionally, the load switch supports 1.5V logic level control and shutdown features in a tiny 0.85 mm x 0.85 mm 4-lead FTDFN package.

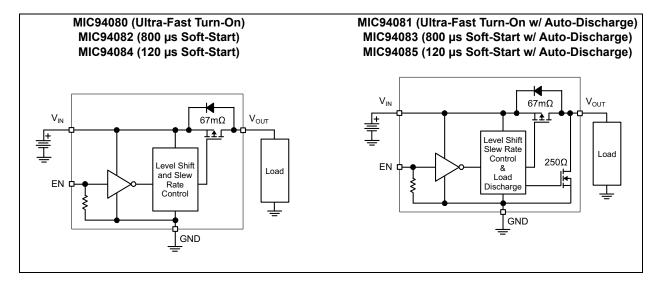
The MIC94080 and MIC94081 feature rapid turn on. The MIC94082 and MIC94083 provide a slew rate controlled soft-start turn-on of 800 μ s, while the MIC94084 and MIC94085 provide a slew rate controlled soft-start turn-on of 120 μ s. The soft-start feature is provided to prevent an in-rush current event from pulling down the input supply voltage.

The MIC94081, MIC94083, and MIC94085 feature an active load discharge circuit which switches in a 250Ω load when the switch is disabled to automatically discharge a capacitive load.

An active pull-down on the enable input keeps the MIC94080/1/2/3/4/5 in a default OFF state until the enable pin is pulled above 1.25V. Internal level shift circuitry allows low voltage logic signals to switch higher supply voltages. The enable voltage can be as high as 5.5V and is not limited by the input voltage.

The MIC94080/1/2/3/4/5 operating voltage range makes them ideal for Lithium ion and NiMH/NiCad/Alkaline battery powered systems, as well as non-battery powered applications. The devices provide low quiescent current and low shutdown current to maximize battery life.

Typical Application Circuits



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Input Voltage (V _{IN}) Enable Voltage (V _{EN})	+6V
Enable Voltage (V _{EN})	+6V
Continuous Drain Current (I _D) (Note 1)	
$T_A = +25^{\circ}C$	±2.0A
T _A = +25°C	±1.5A
Pulsed Drain Current (I _{DP}) (Note 2)	±6.0A
Continuous Diode Current (I _S) (Note 3)	–50 mA
Storage Temperature (Tc)	–55°C to +150°C
ESD Rating (HBM, Note 4)	3 kV
Operating Ratings ††	
Input Voltage (V _{IN})	+1.7V to +5.5V
Junction Temperature Range (T _J)	
Package Thermal Resistance	
4-Ld FTDFN 0.85 mm x 0.85 mm (θ _{JA})	140°C/W
4-Ld FTDFN 0.85 mm x 0.85 mm (θ_{JC})	

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

†† Notice: The device is not guaranteed to function outside its operating ratings.

Note 1: With thermal contact to PCB. See Thermal Considerations section.

- 2: Pulse width <300 µs with <2% duty cycle.
- 3: Continuous body diode current conduction (reverse conduction, i.e. V_{OUT} to V_{IN}) is not recommended.
- **4:** Devices are ESD sensitive. Handling precautions recommended. Human body model, 1.5 k Ω in series with 100 pF.

ELECTRICAL CHARACTERISTICS

Electrical Characteristics: $T_A = +25^{\circ}C$, **bold** values indicate $-40^{\circ}C \le T_A \le +85^{\circ}C$, unless noted.

Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions
Enable Threshold Voltage	V _{EN_TH}	0.4	_	1.25	V	V_{IN} = 1.7V to 4.5V, I_{D} = -250 μ A
Quiagaant Current	lQ	_	0.1	1	•	$V_{IN} = V_{EN} = 5.5V$, $I_D = OPEN$ Measured on V_{IN} MIC94080/1
Quiescent Current		_	8	15	μA	$V_{IN} = V_{EN} = 5.5V$, $I_D = OPEN$ Measured on V_{IN} MIC94082/3/4/5
Enable Input Current	I _{EN}	_	2.8	4	μA	$V_{IN} = V_{EN} = 5.5V$, $I_D = OPEN$
Quiescent Current (Shutdown)	I _{SHUT-Q}	_	0.02	1	μA	V_{IN} = +5.5V, V_{EN} = 0V, I_D = OPEN Measured on V_{IN} , Note 1
OFF State Leakage Current	I _{SHUT-SWITCH}	_	0.02	1	μΑ	V_{IN} = +5.5V, V_{EN} = 0V, I_{D} = SHORT Measured on V_{IN} , Note 1
		_	67	115		V_{IN} = +5.0V, I_{D} = -100 mA, V_{EN} = 1.5V
		_	70	130		V_{IN} = +4.5V, I_{D} = -100 mA, V_{EN} = 1.5V
P-Channel	_D		80	165	m0	V_{IN} = +3.6V, I_{D} = -100 mA, V_{EN} = 1.5V
Drain-to-Source ON Resistance	R _{DS(ON)}	_	110	225	mΩ	V_{IN} = +2.5V, I_{D} = -100 mA, V_{EN} = 1.5V
		_	175	350		V_{IN} = +1.8V, I_D = -100 mA, V_{EN} = 1.5V
		_	200	375		V_{IN} = +1.7V, I_{D} = -100 mA, V_{EN} = 1.5V
Turn-Off Resistance	R _{SHUTDOWN}	_	250	400	Ω	V_{IN} = +3.6V, I_{TEST} = 1 mA, V_{EN} = 0V MIC94081/3/5
Dynamic Electrical Cha	aracteristics					
	t _{ON_DLY}	_	0.4	1.5	μs	V_{IN} = +3.6V, I_{D} = -100 mA, V_{EN} = 1.5V MIC94080, MIC94081
Turn-On Delay		200	600	1500		V_{IN} = +3.6V, I_{D} = -100 mA, V_{EN} = 1.5V MIC94082, MIC94083
		65	110	165		V_{IN} = +3.6V, I_{D} = -100 mA, V_{EN} = 1.5V MIC94084, MIC94085
	t _{ON_} RISE	_	0.4	1.5	μs	V_{IN} = +3.6V, I_{D} = -100 mA, V_{EN} = 1.5V MIC94080, MIC94081
Turn-On Rise Time		400	800	1500		V _{IN} = +3.6V, I _D = -100 mA, V _{EN} = 1.5V MIC94082, MIC94083
		65	120	175		V_{IN} = +3.6V, I_{D} = -100 mA, V_{EN} = 1.5V MIC94084, MIC94085
Turn-Off Delay Time	t _{OFF_DLY}	_	60	200	ns	V_{IN} = +3.6V, I_D = -100 mA, V_{EN} = 0V
Turn-Off Fall Time	t _{OFF_FALL}	_	20	100	ns	V_{IN} = +3.6V, I_{D} = -100 mA, V_{EN} = 0V

Note 1: Measured on the MIC94080YFT.

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions	
Temperature Ranges							
Junction Temperature Range	T_J	-40	_	+125	°C	_	
Storage Temperature Range	T _S	-55	_	+150	°C	_	
Package Thermal Resistances							
Thermal Resistance, 4-Ld FTDFN 0.85 mm x 0.85 mm	θ_{JA}	_	140	_	°C/W	_	
Thermal Resistance, 4-Ld FTDFN 0.85 mm x 0.85 mm	$\theta_{\sf JC}$	_	85	_	°C/W	_	

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

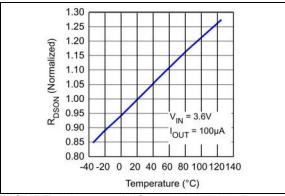


FIGURE 2-1: MIC94080/1/2/3/4/5 R_{DS(ON)} Variance vs. Temperature.

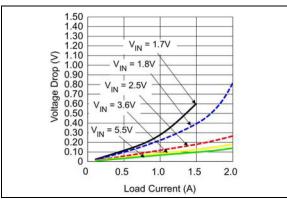


FIGURE 2-2: MIC94080/1/2/3/4/5 Voltage Drop vs. Load Current.

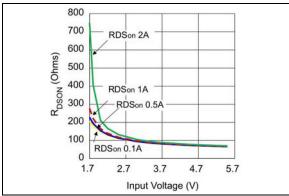


FIGURE 2-3: MIC94080/1/2/3/4/5 On Resistance vs. Input Voltage.

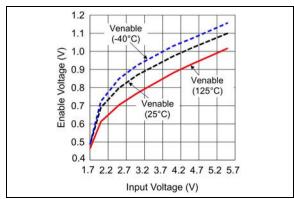


FIGURE 2-4: MIC94080/1 Enable Threshold vs. Input Voltage.

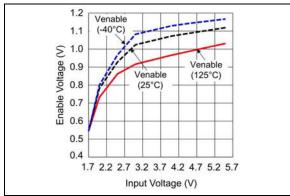


FIGURE 2-5: MIC94082/3/4/5 Enable Threshold vs. Input Voltage.

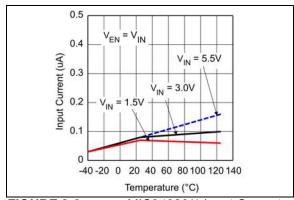


FIGURE 2-6: MIC94080/1 Input Current vs. Temperature.

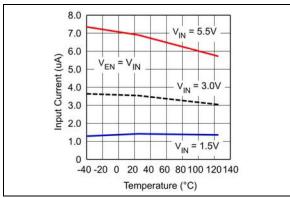


FIGURE 2-7: MIC94082/3/4/5 Input Current vs. Temperature.

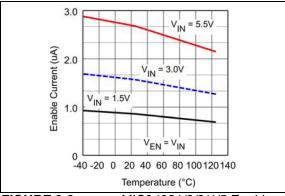


FIGURE 2-8: MIC94081/2/3/4/5 Enable Current vs. Temperature.

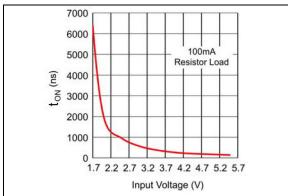


FIGURE 2-9: MIC94080/1 t_{ON} Delay vs. Input Voltage.

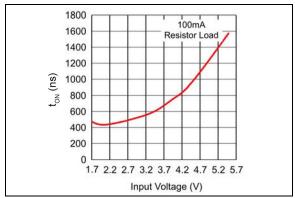


FIGURE 2-10: MIC94082/3 t_{ON} Delay vs. Input Voltage.

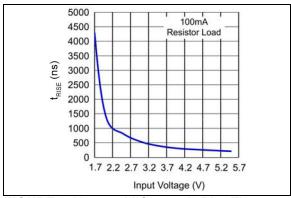


FIGURE 2-11: MIC94080/1 Rise Time vs. Input Voltage.

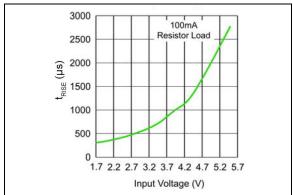


FIGURE 2-12: MIC94082/3 Rise Time vs. Input Voltage.

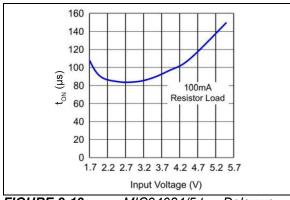


FIGURE 2-13: Input Voltage.

MIC94084/5 t_{ON} Delay vs.

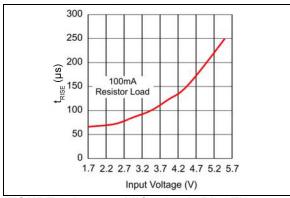


FIGURE 2-14: Input Voltage.

MIC94084/5 Rise Time vs.

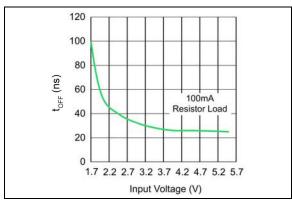


FIGURE 2-15: MIC94080/1/2/3/4/5 t_{OFF} Delay vs. Input Voltage.

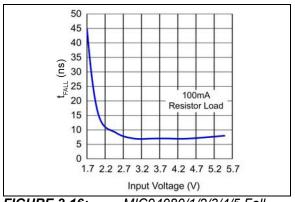


FIGURE 2-16: MIC94080/1/2/3/4/5 Fall Time vs. Input Voltage.

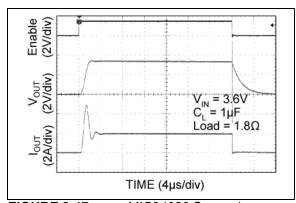


FIGURE 2-17: MIC94080 Scope 1.

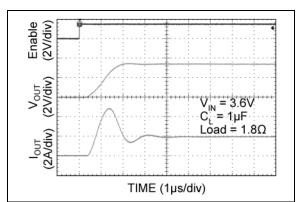


FIGURE 2-18: MIC94080 Scope 2.

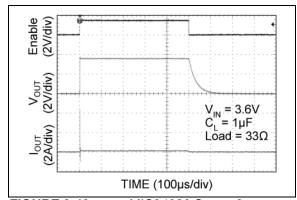


FIGURE 2-19: MIC94080 Scope 3.

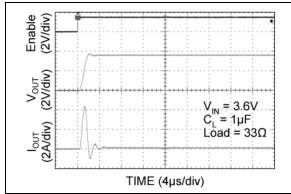


FIGURE 2-20: MIC94080 Scope 4.

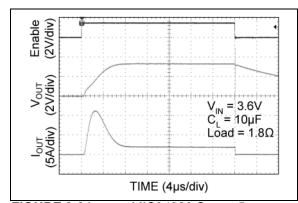


FIGURE 2-21: MIC94080 Scope 5.

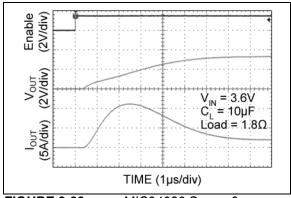


FIGURE 2-22: MIC94080 Scope 6.

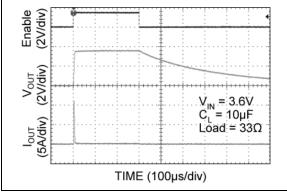


FIGURE 2-23: MIC94080 Scope 7.

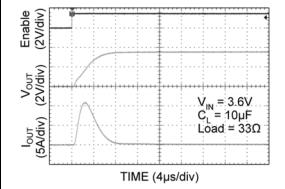


FIGURE 2-24: MIC94080 Scope 8.

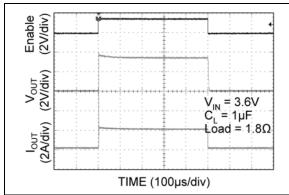


FIGURE 2-25: MIC94081 Scope 1.

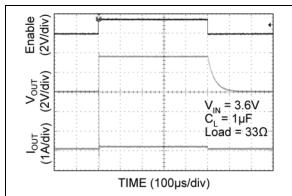


FIGURE 2-26: MIC94081 Scope 2.

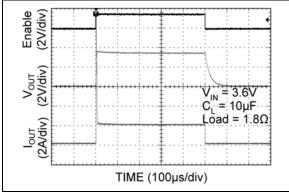


FIGURE 2-27: MIC94081 Scope 3.

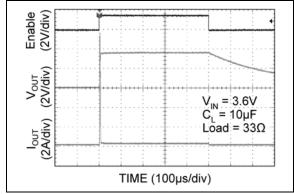


FIGURE 2-28: MIC94081 Scope 4.

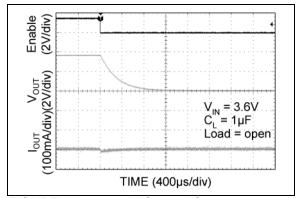


FIGURE 2-29: MIC94081 Scope 5.

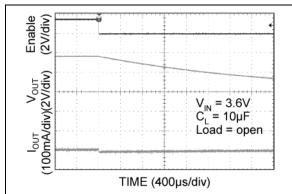


FIGURE 2-30: MIC94081 Scope 6.

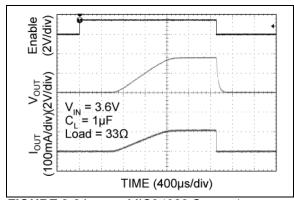


FIGURE 2-31: MIC94082 Scope 1.

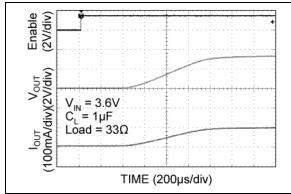


FIGURE 2-32: MIC94082 Scope 2.

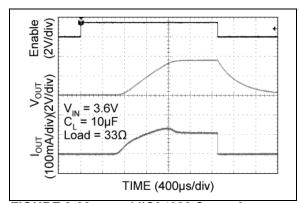


FIGURE 2-33: MIC94082 Scope 3.

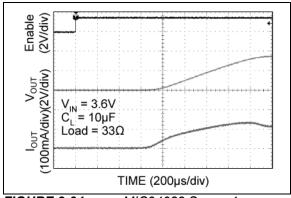


FIGURE 2-34: MIC94082 Scope 4.

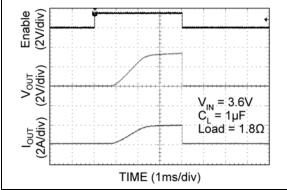


FIGURE 2-35: MIC94082 Scope 5.

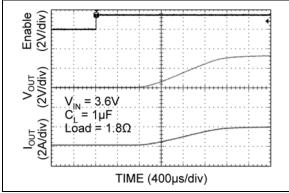


FIGURE 2-36: MIC94082 Scope 6.

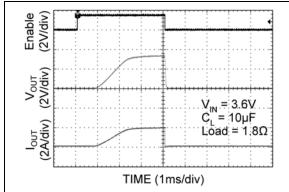


FIGURE 2-37:

MIC94082 Scope 7.

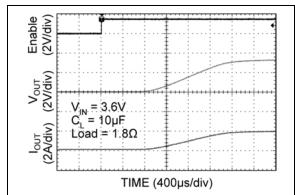


FIGURE 2-38:

MIC94082 Scope 8.

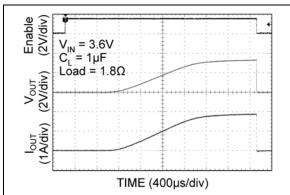


FIGURE 2-39:

MIC94083 Scope 1.

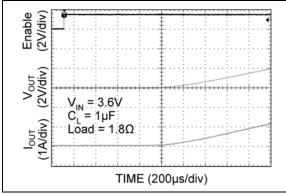


FIGURE 2-40:

MIC94083 Scope 2.

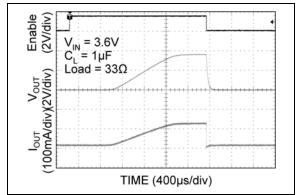


FIGURE 2-41:

MIC94083 Scope 3.

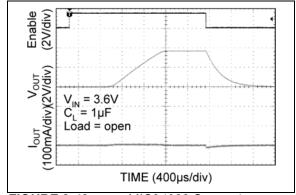


FIGURE 2-42:

MIC94083 Scope 4.

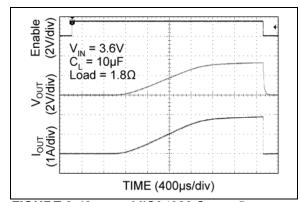


FIGURE 2-43: MIC94083 Scope 5.

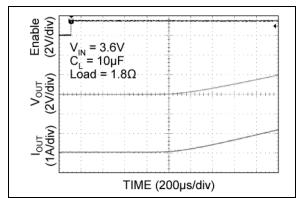


FIGURE 2-44: MIC94083 Scope 6.

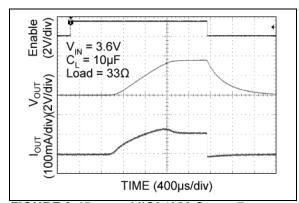


FIGURE 2-45: MIC94083 Scope 7.

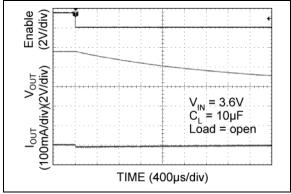


FIGURE 2-46: MIC94083 Scope 8.

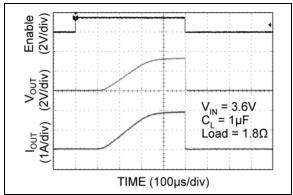


FIGURE 2-47: MIC94084 Scope 1.

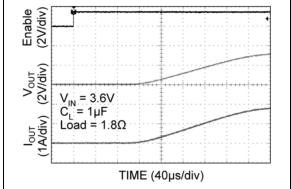
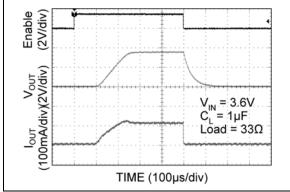
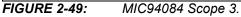


FIGURE 2-48: MIC94084 Scope 2.





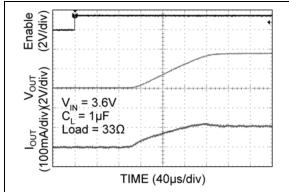


FIGURE 2-50: MIC94084 Scope 4.

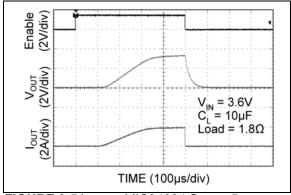


FIGURE 2-51: MIC94084 Scope 5.

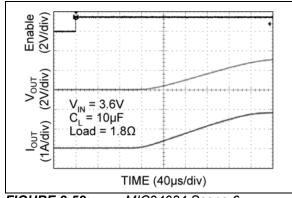


FIGURE 2-52: MIC94084 Scope 6.

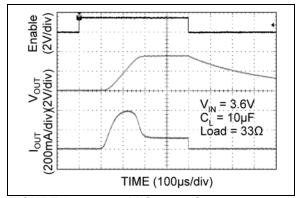


FIGURE 2-53: MIC94084 Scope 7.

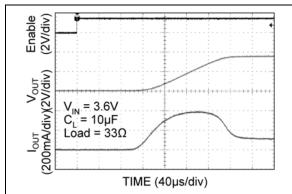


FIGURE 2-54: MIC94084 Scope 8.

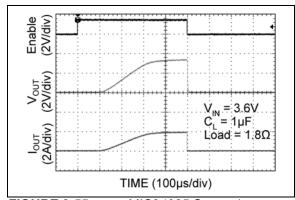


FIGURE 2-55: MIC94085 Scope 1.

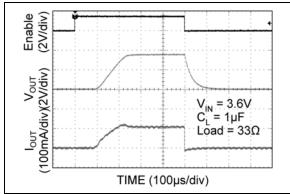


FIGURE 2-56: MIC94085 Scope 2.

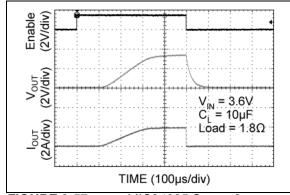


FIGURE 2-57: MIC94085 Scope 3.

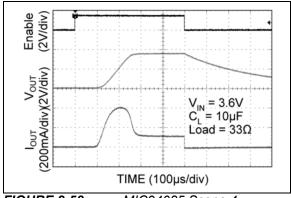


FIGURE 2-58: MIC94085 Scope 4.

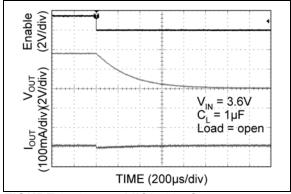


FIGURE 2-59: MIC94085 Scope 5.

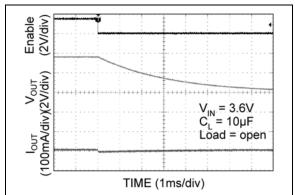


FIGURE 2-60: MIC94085 Scope 6.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description		
1	V _{OUT}	Drain of P-Channel MOSFET.		
2	GND	Ground. Should be connected to electrical ground.		
3	V _{IN}	Source of P-Channel MOSFET.		
4	EN	Enable (Input): Active-high CMOS/TTL control input for switch. Internal ~2 M Ω pull-down resistor. Output will be off if this pin is left floating.		

4.0 APPLICATION INFORMATION

4.1 Power Switch SOA

The safe operating area (SOA) curve represents the boundary of maximum safe operating current and maximum safe operating junction temperature.

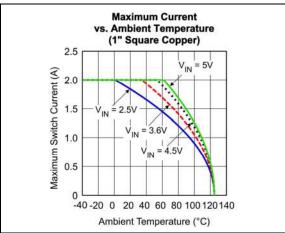


FIGURE 4-1: SOA Graph.

The curves above show the SOA for various V_{IN} values mounted on a typical one-layer, 1 square inch copper board.

4.2 Power Dissipation Considerations

As with all power switches, the current rating of the switch is limited mostly by the thermal properties of the package and the PCB on which it's mounted. There is a simple Ohm's law type relationship between thermal resistance, power dissipation, and temperature that are analogous to an electrical circuit.

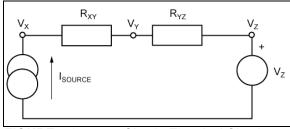


FIGURE 4-2: Simple Electrical Circuit.

From this simple circuit, one can calculate V_X if one knows I_{SOURCE} , V_Z , and the resistor values for R_{XY} and R_{YZ} using Equation 4-1.

EQUATION 4-1:

$$V_X = I_{SOURCE} \times (R_{XY} + R_{YZ}) + V_Z$$

Thermal circuits can be considered using these same rules and can be drawn similarly by replacing current sources with power dissipation (in Watts), resistance with thermal resistance (in °C/W), and voltage sources with temperature (in °C).

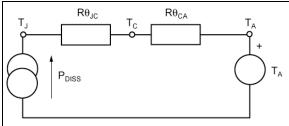


FIGURE 4-3:

Simple Thermal Circuit.

By replacing the variables in the equation for V_X , one can find the junction temperature (T_J) from power dissipation, ambient temperature, and then know thermal resistance of the PCB $(R\theta_{CA})$ and the package $(R\theta_{JC})$.

EQUATION 4-2:

$$T_J = P_{DISS} \times (R\theta_{JC} + R\theta_{CA}) + T_A$$

 P_{DISS} is calculated as I_{SWITCH}^2 x $R_{SW(MAX)}$. $R\theta_{JC}$ is found in the Temperature Specifications section of this data sheet and $R\theta_{CA}$ (the PCB thermal resistance) values for various PCB copper areas is discussed in Designing with Low Dropout Voltage Regulators.

4.2.1 AN EXAMPLE

A switch is intended to drive a 1A load and is placed on a PCB that has a ground plane area of at least 25 mm by 25 mm (625 mm 2). The voltage source is a Li-ion battery with a lower operating threshold of 3V and the ambient temperature of the assembly can be up to 50°C.

Summary of variables:

- I_{SW} = 1A
- V_{IN} = 3V to 4.2V
- T_A = 50°C
- $R\theta_{JC} = 85^{\circ}C/W$
- $R\theta_{CA} = 53^{\circ}C/W$ (as read from Figure 4-4)

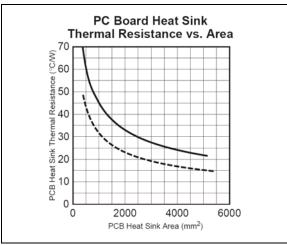


FIGURE 4-4:

Excerpt from the LDO Book.

EQUATION 4-3:

$$P_{DISS} = I_{SW}^{2} \times R_{SW(MAX)}$$

The worst case switch resistance ($R_{SW(MAX)}$) at the lowest V_{IN} of 3V is not available in the data sheet, so the next lowest value of V_{IN} is used.

 $R_{SW(MAX)}$ at 2.5V is 200 $m\Omega.$

An additional consideration is to allow for the maximum junction temperature of 125°C. If this was a calculation for the worst case $R_{SW(MAX)}$ for 25°C, the actual worst case resistance in this case can be 30% higher (see Figure 2-1). However, 200 $m\Omega$ is the maximum over temperature. Therefore:

EQUATION 4-4:

$$T_J = 1^2 \times 0.2 \times (85 + 53) + 50 = 78^{\circ}C$$

This is below the maximum of 125°C.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information



TABLE 5-1: MARKING CODES

Part Number	Marking Code	Features
MIC94080YFT-TR	C1	Fast Turn-On
MIC94081YFT-TR	C2	Fast Turn-On, Load Discharge
MIC94082YFT-TR	C5	800 μs Soft-Start
MIC94083YFT-TR	C7	800 μs Soft-Start, Load Discharge
MIC94084YFT-TR	C0	120 μs Soft-Start
MIC94085YFT-TR	1C	120 µs Soft-Start, Load Discharge

Legend:	XXX	Product code or customer-specific information
	Υ	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	e 3	Pb-free JEDEC [®] designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3)
		can be found on the outer packaging for this package.
	•, ▲ , ▼ mark).	Pin one index is identified by a dot, delta up, or delta down (triangle

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.

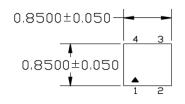
Underbar (_) and/or Overbar (¯) symbol may not be to scale.

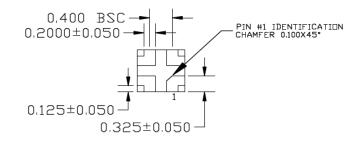
4-Lead FTDFN Package Outline & Recommended Land Pattern

TITLE

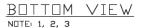
4 LEAD FTDFN 0.85x0.85 mm PACKAGE (Flip Chip) OUTLINE & RECOMMENDED LAND PATTERN

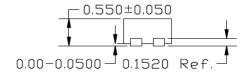
DRAWING #	FTDFN085085-4LD-PL-1	UNIT	MM
LEAD FRAME	Copper Alloy	LEAD FINISH	NiPdAu











NOTE:

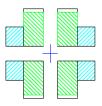
- 1. MAX PACKAGE WARPAGE IS 0.05 MM
- 2. MAX ALLOWABLE BURR IS 0.076 MM IN ALL DIRECTIONS
- 3. PIN #1 IS ON TOP WILL BE LASER MARKED
- 4. GREEN COLORED RECTANGLES (SHADED AREA) REPRESENT SOLDER STENCIL OPENING ON EXPOSED METAL TRACE.
- 5. CYAN COLORED RECTANGLES (SHADED AREA) REPRESENT OPTIONAL SOLDER STENCIL OPENING.

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging.

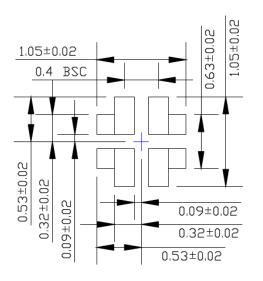
POD-Land Pattern drawing #FTDFN085085-4LD-PL-1

RECOMMENDED LAND PATTERN

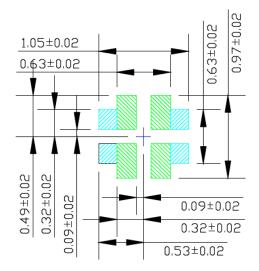
N□TE: 4, 5



STACKED-UP







SOLDER STENCIL OPENING

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging.

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (March 2019)

- Converted Micrel document MIC94080/1/2/3/4/5 to Microchip data sheet template DS20006118A.
- Minor grammatical text changes throughout.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

				Example	es:	
Device Part No.	X Junction Temp. Range	XX Package	- XX Media Type		080YFT-TR: 081YFT-TR:	MIC94080, -40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel MIC94081, -40°C to +125°C
Device:	MIC94081: MIC94082: MIC94083: MIC94084: MIC94085:	67 mΩ R _{DS(ON)} 2A Hig with Fast Turn-On 67 mΩ R _{DS(ON)} 2A Hig with Fast Turn-On and 67 mΩ R _{DS(ON)} 2A Hig with 800 μs Soft-Start 67 mΩ R _{DS(ON)} 2A Hig with 800 μs Soft-Start 67 mΩ R _{DS(ON)} 2A Hig with 800 μs Soft-Start 67 mΩ R _{DS(ON)} 2A Hig with 120 μs Soft-Start 67 mΩ R _{DS(ON)} 2A Hig with 120 μs Soft-Start 67 mΩ R _{DS(ON)} 2A Hig with 120 μs Soft-Start 67 mΩ R _{DS(ON)} 2A Hig with 120 μs Soft-Start 67	h-Side Load Switch Load Discharge h-Side Load Switch h-Side Load Switch and Load Discharge h-Side Load Switch h-Side Load Switch	d) MIC94(082YFT-TR: 083YFT-TR: 084YFT-TR:	Temperature Range, 4-Lead FTDFN, 5,000/Reel MIC94082, -40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel MIC94083, -40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel MIC94084, -40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel
Junction Temperature Range:	Y = -40°C	to +125°C, RoHS-Con	npliant		085YFT-TR:	MIC94085, –40°C to +125° Temperature Range, 4-Lead FTDFN, 5,000/Reel
Package: Media Type:	FT = 4-Lead	d 0.85 mm x 0.85 mm F	FTDFN	Note 1:	catalog part nu used for orderi the device pac	identifier only appears in the mber description. This identifier is ng purposes and is not printed or kage. Check with your Microchip r package availability with the online.

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